

3.8 x 1.2 x 0.6 Red SMD, Tape and Reel

PACKAGE OUTLINES



RECOMMEND PAD LAYOUT



NOTES:

1. All dimensions are in millimeters tolerance is ±0.2mm unless otherwise noted; Angle±0.5. Unit=mm.

Part Number	Material	Lens Color	
		Emitted	Lens
L234NEC-TR	AlGaInP	Red	Water Clear



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ABSOLUTE MAXIMUM RATINGS	(Ta=25°C)		
Parameter	Symbol	Ratings	Unit
Power Dissipation	PD	72	mW
Peak Forward Current (Duty 1/11@10KHz)	lfp	60	mA
Forward Current	lf	30	mA
Reverse Current @ 5V	Ir	10	μA
Electrostatic Discharge	ESD	2000	V
Operating temperature range	Topr	-40~+85	°C
Storage temperature range	Tstg	-40~+100	°C

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Luminous Intensity	lv	I _F =20mA	200	320		mcd
Dominant Wavelength	λD			625		nm
Spectral Line Half-Width	Δλ			20		nm
Forward Voltage	Vf		1.5		2.4	V
Viewing angle	20 1⁄2			120		Deg

*Note: 1. The forward voltage data did not include $\pm 0.1V$ testing tolerance.

2. The luminous intensity data did not include $\pm 15\%$ testing tolerance.



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TYPICAL ELECTRO-OPTICAL CHARACTERISTIC CURVES

Fig.1 Forward current vs. Forward Voltage





Fig.2 Luminous Intensity vs. Forward Current

Forward Current(mA)

Fig.3 Forward Voltage vs. Temperature

Fig.4 Luminous Intensity vs. Temperature







Fig.6 Directive Radiation





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LUMINOUS INTENSITY CLASSIFICATION

BIN CODE	lv(mcd)	@ 20mA
BINCODE	Min.	Max.
S	200	320
т	320	500
U	500	800



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CARRIER TAPE DIMENSION



Note: The tolerances unless mentioned are ±0.1mm, Angle ±0.5; Unit=mm

REEL DIMENSIONS



Notes: 1. 3000 pieces per reel.



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RECOMMENDED SOLDERING CONDITIONS

- Hand solder Basic spec is ≤ 320°C 3 sec one time only.
- 2. Wave solder



3. PB-Free reflow solder



Notes:

- 1. Reflow soldering should not be done more than two times.
- 2. When soldering, do not put stress on the LEDs during heating.
- 3. After soldering, do not warp the circuit board.



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PRECAUTIONS FOR USE

Storage Time:

1. The operation of temperatures and RH are: 5°C~35°C, RH60%.

2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year (from production date).

3. If opened more than one week in an atmosphere 5°C~35°C, RH60%, they should be treated at 60°C±5°C for 15hrs.

Drive Method:

LED is a current operated device, and therefore, require some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in a series with the LED.

Consider worst case voltage variations that could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.



(A) Recommended circuit.

(B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or antielectrostatic glove is recommended when handling these LEDs. All devices and machinery must be properly grounded.



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RELIABILITY TEST:

(1) Test items and results

Classification	Test Item	Test Conditions	Number of Damaged
	Operating Life Test	 Ta=under room temperature as per data sheet maximum rating If=20mA t=1000 hrs 	0/22
ice Test	High Temperature Storage Test	1. Ta=105°C±5°C 2. t=500 hrs	0/22
Endurance Test	Low Temperature Storage Test	1. Ta=40°C±5°C 2. t=1000 hrs	0/22
	High Temperature High Humidity Storage Test	1. IR-Reflow in-board, 2 times 2. Ta=85°C±5°C 3. RH=90%~95% 4. t=500hrs±2hrs	0/22
Environmental Test	Thermal Shock Test	 IR-Reflow in-board, 2 times Ta=105°C±5°C & -40°C±5°C (30min) (30min) Total 100 cycles 	0/22
	Reflow Soldering Test	1. Tsol=260°C±5°C 2. Dwell time = 10 max	0/22
	Temperature Cycling	1. 105°C ~ 25°C ~ -40°C 30 mins 15 mins 30 mins 2. 100 cycles	0/22

(2) Criteria for judging the damage

Itom	Qumbal	Test Conditions	Criteria for Judgement		
Item Symbol		Test Conditions	Min.	Max.	
Forward Voltage	Vf	lf=20mA		U.S.L. x 1.2	
Reverse Current	lr	Vr=5V		U.S.L. x 2.0	
Luminous Intensity	lv	lf=20mA	L.S.L. x 0.5	-	

Note:

1. U.S.L.: Upper Standard Level. 2. L.S.L: Lower Standard Level